USB 3.0 MicroAB UPSTREAM INTERFACE

1) USB 2.0 ULPI_D_P/N signals differentially routed @ 90 degrees; USB 3.0 UPSTREAM interface routed @ 90 degrees for differential. 3) ULPI_VBUS >30 mil thick trace for current.

Layout Note: Place R154 pin 2 pad directly on clock trace to U14.
LPDDR4 16Gb (2GB) RAM
POINT-TO-POINT: NO DDR TERM RESISTORS
40 OHM INTERFACE IMPEDANCE

MT3DS512M32D2DS-053 AIT:D

contre connected to maintain backwards DDR compatibility.
I/O EXPANSION HEADERS, ON/OFF CONTROLLER

Power On switch. Position 2-3: board powers up when power applied.

*Design Note: PB_N has 100K internal pullup to VCC. KILL_N is floating and must be pulled up to Vcc+1.8V value (as shown).

**ROCKY PMIC #1**

**Sheet Title:**

- **Variant:** 
- **Date:** 3/1/2019
- **Time:** 7:57:28 AM
- **Position:** 30

**I2C Address Offset = +3. Address: 0x13, 0x43.**

**NOTE:** MTP resistor set to allow +3 address skip.

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**ROCKY PMIC #1**

- **+5.0V to GND**
- **+5.0V to GND**
- **+5.0V to GND**
- **+5.0V to GND**

**I2C Address Offset = +3. Address: 0x13, 0x43.**

**NOTE:** MTP resistor set to allow +3 address skip.
MANHATTAN PMIC #3

MAIN POWER +8v - 16 VIN

BOARD +5.0V MAIN, 6A Max

For Bode plot testing

12C Address Offset = +5.
Addresses: 0x15, 0x45.

NOTE: MTP resistor set to allow +5 address skip.

Layout Note: Place JP1 near to Power In jack.

Address: 0x15, 0x45.
Mechanicals:

- ESD Bag
- XXX-XXX-PCB-X (PCB PN (In Copper))

Mounting Holes:

- Mounting Holes
  - MTG1
  - MTG2
  - MTG3
  - MTG4

GND Test Points:

- Ground Test Points
  - TP34
  - TP35

Assembly:

- Label_ESD1
- Label, Serial Number
- Label1
- Label, Product
- Label2
- Label, ESD

PCB PN (In Copper):

- SS1
- SS2
- SS3

RoHS 2-Silk Screen:

- SS1
- SS2
- SS3

FCC - Silk Screen:

- SS3

Trash Can-Silk Screen:

- SS2

COESD1

COPCB PN (In Copper)1

COSS1 COSS2 COSS3

PITP3401

COTP34

PITP3501

COTP35

PIMTG101 PIMTG201 PIMTG301 PIMTG401

PITP3401 PITP3501